

Soldering and reflow considerations

Lead free wave solder profile

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T _{smax} to T _p)	3° C/second max.	3° C/second max.
Preheat <ul style="list-style-type: none"> - Temperature Min (T_{smin}) - Temperature Max (T_{smax}) - Time (T_{smin} to T_{smax}) (t_s) 	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-180 seconds
Time maintained above: <ul style="list-style-type: none"> - Temperature (T_L) - Time (t_L) 	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak Temperature (T _p)	220°C	245°C
Time within 5°C of actual Peak Temperature (t _p) ²	10-30 seconds	20-40 seconds
Ramp-down Rate	6 °C/second max.	6 °C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5 °C of actual peak temperature (t_p) specified for the reflow profiles is a “supplier” minimum and “user” maximum.

